

Technical Data Sheet

1.6mm Round Subminiature Chip LED

HIR26-21C/L423/CT(XY)

Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel.
- Pb free
- The product itself will remain within RoHS compliant version.



Descriptions

HIR26-21C/L423/CT(XY) is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view resin

The device is spectrally matched with silicon photodiode and phototransistor

Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- Infrared applied system

Device Selection Guide

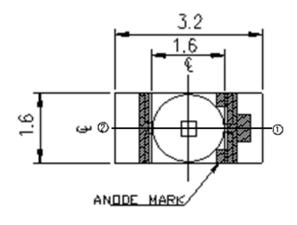
Part No.	Chip	Resin Color	
	Material	Kesiii Color	
HIR	GaAlAs	Water clear	

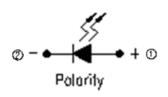
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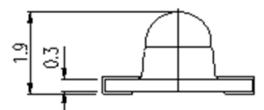


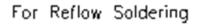
Package Dimensions

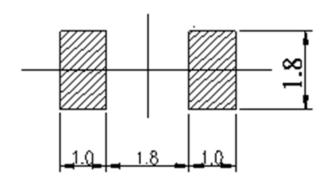


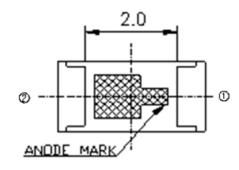


- ① Anode
- (2) Cathode









Notes: 1.All dimensions are in millimeters

2.Tolerances unless dimensions ±0.1 mm



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I_{F}	65	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-25 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Soldering Temperature	T_{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	110	mW

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	Ie	$I_F=20 \text{ mA}$	14.0	16.0		mW/sr
Peak Wavelength	λp	$I_F=20 \text{ mA}$		850		nm
Spectral Bandwidth	Δλ	I _F =20 mA		30		nm
Forward Voltage	V_{F}	I _F =20 mA		1.45	1.70	V
Reverse Current	I_R	$V_R=5 V$			10	μ A
View Angle	2 \theta 1/2	I _F =20 mA		20		deg

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Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

Ambient Temperature

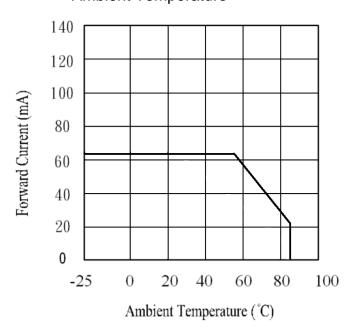


Fig.2 Spectral Distribution

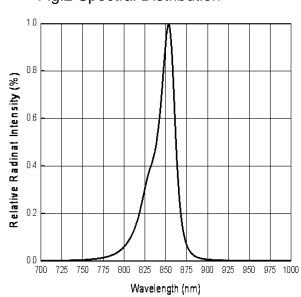


Fig.3 Forward Current vs.
Forward Voltage

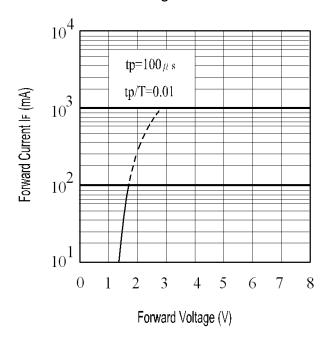
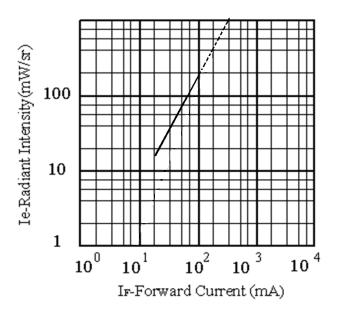


Fig.4 Radiant Intensity vs.
Forward Current



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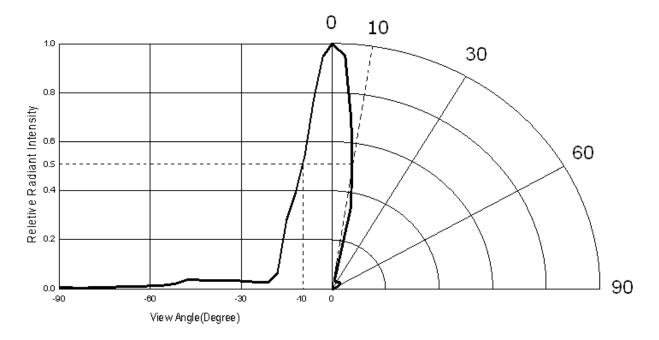
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Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs. View Angle



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Precautions For Use

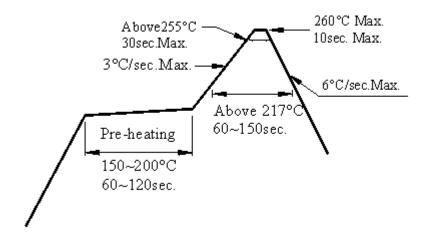
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 168 hours under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : $60\pm5^{\circ}$ C for 24 hours.

- 3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

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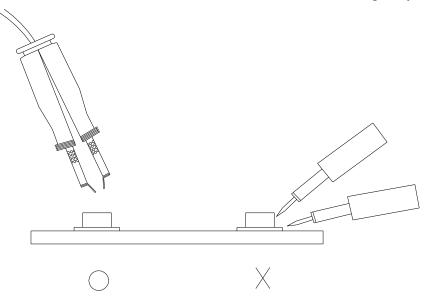


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

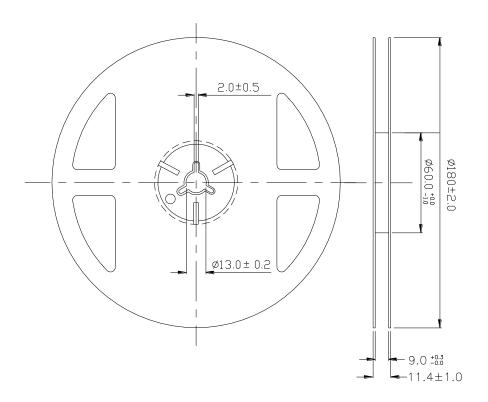


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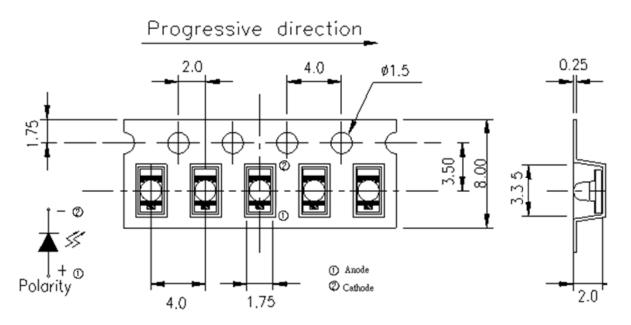
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Reel Dimensions



Carrier Tape Dimensions: Loaded quantity 1,500 PCS per reel:



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

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Label Form Specification



CPN: Customer's Production Number

P/N: Production Number **QTY: Packing Quantity**

CAT: Ranks

HUE: Peak Wavelength

EF: Reference

LOT No: Lot Number

Notes

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.

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